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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

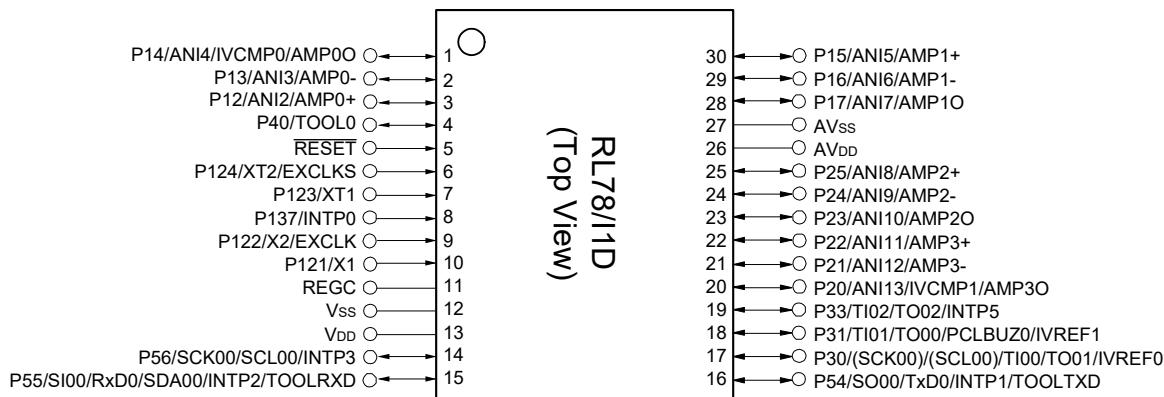
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I ² C, UART/USART
Peripherals	LVD, POR, WDT
Number of I/O	19
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 12x8/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	30-LSSOP (0.240", 6.10mm Width)
Supplier Device Package	30-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f117a8gsp-50

1.3.3 30-pin products

- <R> • 30-pin plastic LSSOP (7.62 mm (300), 0.65 mm pitch)



Caution 1. Connect the REGC pin to Vss pin via a capacitor (0.47 to 1 μ F).

Caution 2. Make AVss pin the same potential as Vss pin.

Caution 3. Make AVdd pin the same potential as Vdd pin.

Remark 1. For pin identification, see 1.4 Pin Identification.

Remark 2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register 0 (PIOR0).

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Item	20-pin	24-pin	30-pin	32-pin	48-pin				
	R5F1176x (x = 8, A)	R5F1177x (x = 8, A)	R5F117Ax (x = 8, A, C)	R5F117Bx (x = A, C)	R5F117Gx (x = A, C)				
Clock output/buzzer output	1	1	1	1	2				
<p>[20-pin, 24-pin products]</p> <ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f_{MAIN} = 20 MHz operation) <p>[30-pin, 32-pin, 48-pin products]</p> <ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f_{MAIN} = 20 MHz operation) • 256 Hz, 512 Hz, 1,024 kHz, 2,048 kHz, 4,096 kHz, 8,192 kHz, 16,384 kHz, 32,768 kHz (subsystem clock generator and RTC/other clock: f_{SR} = 32.768 kHz operation) 									
12-bit resolution A/D converter	6 channels	6 channels	12 channels	12 channels	17 channels				
Comparator (Window Comparator)	2 channels								
Operational amplifier	2 channels		4 channels						
Data Operation Circuit (DOC)	Comparison, addition, and subtraction of 16-bit data								
Serial interface	<p>[20-pin, 30-pin products]</p> <ul style="list-style-type: none"> • CSI: 1 channel/UART: 1 channel/simplified I²C: 1 channel <p>[24-pin, 32-pin, 48-pin products]</p> <ul style="list-style-type: none"> • CSI: 2 channels/UART: 1 channel/simplified I²C: 2 channels 								
<R> Data transfer controller (DTC)	16 sources	20 sources	19 sources	20 sources	22 sources				
<R> Event link controller (ELC)	Event input: 15 Event trigger output: 5	Event input: 17 Event trigger output: 5	Event input: 17 Event trigger output: 7	Event input: 17 Event trigger output: 7	Event input: 20 Event trigger output: 7				
Vectored interrupt sources	Internal	22	22	24	24				
	External	3	5	5	8				
Key interrupt	—	3	—	3	4				
Reset	<ul style="list-style-type: none"> • Reset by <u>RESET</u> pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution Note • Internal reset by RAM parity error • Internal reset by illegal-memory access 								
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 ± 0.04V (T_A = -40 to +85°C) • Power-down-reset: 1.50 ± 0.04 V (T_A = -40 to +85°C) 								
Voltage detector	Power on	1.67 V to 3.13 V (12 stages)							
	Power down	1.63 V to 3.06 V (12 stages)							
On-chip debug function	Provided (Enable to tracing)								
Power supply voltage	V _{DD} = 1.6 to 3.6 V								
Operating ambient temperature	T _A = -40 to +105°C								

The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution is not issued by emulation with the in-circuit emulator or on-chip debug emulator.

2. ELECTRICAL SPECIFICATIONS

Caution 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

Caution 2. The pins mounted depend on the product. Refer to 2.1 Port Functions to 2.2.1 Functions for each product in the RL78/I1D User's Manual.

Caution 3. Please contact Renesas Electronics sales office for derating of operation under $T_A = +85$ to $+105^\circ\text{C}$. Derating is the systematic reduction of load for the sake of improved reliability.

Caution 4. When operating temperature exceeds 85°C , only HS (high-speed main) mode can be used as the flash operation mode. Regulator mode should be used with the normal setting ($\text{MCSEL} = 0$).

($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq AV_{DD} = V_{DD} \leq 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0 \text{ V}$)

($T_A = +85$ to $+105^\circ\text{C}$, $2.4 \text{ V} \leq AV_{DD} = V_{DD} \leq 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0 \text{ V}$)

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Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output current, low Note 1	I _{OL1}	Per pin for P00 to P04, P30 to P33, P40, P50 to P57, P130	TA = -40 to $+85^\circ\text{C}$			20.0 Note 2
			TA = $+85$ to $+105^\circ\text{C}$			8.5 Note 2
		Per pin for P60 to P63				15.0 Note 2
		Total of P00 to P04, P40, P130 (When duty $\leq 70\%$ Note 3)	2.7 V $\leq V_{DD} \leq 3.6 \text{ V}$			15.0
			1.8 V $\leq V_{DD} < 2.7 \text{ V}$			9.0
			1.6 V $\leq V_{DD} < 1.8 \text{ V}$			4.5
		Total of P30 to P33, P50 to P57, P60 to P63 (When duty $\leq 70\%$ Note 3)	2.7 V $\leq V_{DD} \leq 3.6 \text{ V}$			35.0
			1.8 V $\leq V_{DD} < 2.7 \text{ V}$			20.0
			1.6 V $\leq V_{DD} < 1.8 \text{ V}$			10.0
		Total of all pins (When duty $\leq 70\%$ Note 3)				50.0
	I _{OL2}	Per pin for P10 to P17, P20 to P25				0.4 Note 2
		Total of all pins (When duty $\leq 70\%$ Note 3)	1.6 V $\leq V_{DD} \leq 3.6 \text{ V}$			5.6

Note 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin.

Note 2. Do not exceed the total current value.

Note 3. Specification under conditions where the duty factor $\leq 70\%$.

The output current value that has changed to the duty factor $> 70\%$ the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

- Total output current of pins = $(I_{OL} \times 0.7)/(n \times 0.01)$

<Example> Where n = 80% and I_{OL} = 10.0 mA

$$\text{Total output current of pins} = (10.0 \times 0.7)/(80 \times 0.01) \approx 8.7 \text{ mA}$$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, Vss = AVss = 0 V)

(TA = +85 to +105°C, 2.4 V ≤ AVDD = VDD ≤ 3.6 V, Vss = AVss = 0 V)

(5/5)

Items	Symbol	Conditions			MIN.	TYP.	MAX.	Unit	
Input leakage current, high	I _{LIH1}	P00 to P04, P30 to P33, P40, P50 to P57, P60 to P63, P130, P137	Vi = V _{DD}				1	μA	
	I _{LIH2}	RESET					1	μA	
	I _{LIH3}	P121 to P124 (X1, X2, EXCLK, XT1, XT2, EXCLKS)		In input port or external clock input			10	μA	
				In resonator connection					
Input leakage current, low	I _{LIL1}	P00 to P04, P30 to P33, P40, P50 to P57, P60 to P63, P130, P137	Vi = V _{SS}				-1	μA	
	I _{LIL2}	RESET					-1	μA	
	I _{LIL3}	P121 to P124 (X1, X2, EXCLK, XT1, XT2, EXCLKS)		In input port or external clock input			-10	μA	
				In resonator connection					
On-chip pull-up resistance	R _U	P00 to P04, P30 to P33, P40, P50 to P57, P130	Vi = V _{SS} , In input port		10	20	100	kΩ	

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

(TA = +85 to +105°C, 2.4 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

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Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I _{D02} Note 2	HALT mode	HS (high-speed main) mode	f _{IH} = 24 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		0.37	1.83	mA
				f _{IH} = 24 MHz Note 4, T _A = +85 to +105°C	V _{DD} = 3.0 V			2.85	
				f _{IH} = 16 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		0.36	1.38	
				f _{IH} = 16 MHz Note 4, T _A = +85 to +105°C	V _{DD} = 3.0 V			2.08	
		LS (low-speed main) mode (MCSEL = 0)	f _{IH} = 8 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		250	710		μA
				V _{DD} = 2.0 V		250	710		
		LS (low-speed main) mode (MCSEL = 1)	f _{IH} = 4 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		204	400		μA
				V _{DD} = 2.0 V		204	400		
		LV (low-voltage main) mode	f _{IH} = 3 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		425	800		μA
				V _{DD} = 2.0 V		425	800		
		LP (low-power main) mode (MCSEL = 1)	f _{IH} = 1 MHz Note 4, T _A = -40 to +85°C	V _{DD} = 3.0 V		192	400		μA
				V _{DD} = 2.0 V		192	400		
				f _{IM} = 1 MHz Note 7, T _A = -40 to +85°C	V _{DD} = 3.0 V		27	100	
				V _{DD} = 2.0 V		27	100		
		HS (high-speed main) mode	f _{MX} = 20 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 3.0 V	Square wave input	0.20	1.55		mA
					Resonator connection	0.40	1.74		
			f _{MX} = 20 MHz Note 3, T _A = +85 to +105°C	V _{DD} = 3.0 V	Square wave input		2.45		
					Resonator connection		2.57		
			f _{MX} = 10 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 3.0 V	Square wave input	0.15	0.86		
					Resonator connection	0.30	0.93		
			f _{MX} = 10 MHz Note 3, T _A = +85 to +105°C	V _{DD} = 3.0 V	Square wave input		1.28		
					Resonator connection		1.36		
		LS (low-speed main) mode (MCSEL = 0)	f _{MX} = 8 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 3.0 V	Square wave input	68	550		μA
					Resonator connection	120	590		
			f _{MX} = 8 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 2.0 V	Square wave input	68	550		
					Resonator connection	120	590		
		LS (low-speed main) mode (MCSEL = 1)	f _{MX} = 4 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 3.0 V	Square wave input	23	128		μA
					Resonator connection	65	200		
			f _{MX} = 1 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 2.0 V	Square wave input	23	128		
					Resonator connection	65	200		
		LP (low-power main) mode (MCSEL = 1)	f _{MX} = 4 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 3.0 V	Square wave input	10	64		μA
					Resonator connection	48	150		
			f _{MX} = 1 MHz Note 3, T _A = -40 to +85°C	V _{DD} = 2.0 V	Square wave input	10	64		
					Resonator connection	48	150		
		Subsystem clock operation	fs _X = 32.768 kHz, T _A = -40°C Note 5	fs _X = 32.768 kHz, T _A = -40°C Note 5	Square wave input	0.24	0.57		μA
					Resonator connection	0.42	0.76		
			fs _X = 32.768 kHz, T _A = +25°C Note 5	fs _X = 32.768 kHz, T _A = +25°C Note 5	Square wave input	0.30	0.57		
					Resonator connection	0.54	0.76		
			fs _X = 32.768 kHz, T _A = +50°C Note 5	fs _X = 32.768 kHz, T _A = +50°C Note 5	Square wave input	0.35	1.17		
					Resonator connection	0.60	1.36		
			fs _X = 32.768 kHz, T _A = +70°C Note 5	fs _X = 32.768 kHz, T _A = +70°C Note 5	Square wave input	0.42	1.97		
					Resonator connection	0.70	2.16		
			fs _X = 32.768 kHz, T _A = +85°C Note 5	fs _X = 32.768 kHz, T _A = +85°C Note 5	Square wave input	0.80	3.37		
					Resonator connection	0.95	3.56		
			fs _X = 32.768 kHz, T _A = +105°C Note 5	fs _X = 32.768 kHz, T _A = +105°C Note 5	Square wave input	1.80	17.10		
					Resonator connection	2.20	17.50		
			f _{L1} = 15 kHz, T _A = -40°C Note 6			0.40	1.22		μA
			f _{L1} = 15 kHz, T _A = +25°C Note 6			0.47	1.22		
			f _{L1} = 15 kHz, T _A = +85°C Note 6			0.80	3.30		
			f _{L1} = 15 kHz, T _A = +105°C Note 6			2.00	17.30		

(Notes and Remarks are listed on the next page.)

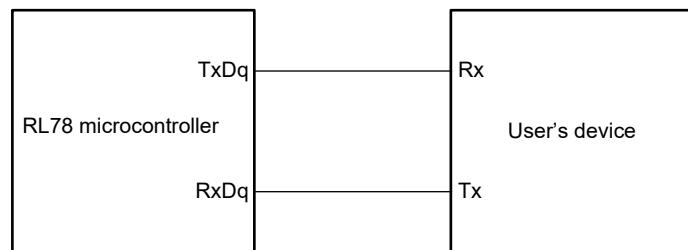
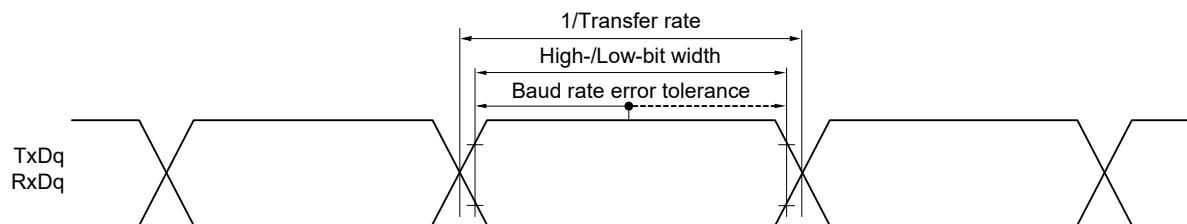
($TA = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq AV_{DD} = V_{DD} \leq 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0 \text{ V}$)

($TA = +85$ to $+105^\circ\text{C}$, $2.4 \text{ V} \leq AV_{DD} = V_{DD} \leq 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0 \text{ V}$)

(4/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current Note 1	I _{DD3} Note 2	STOP mode Note 3	TA = -40°C		0.16	0.51	μA
			TA = $+25^\circ\text{C}$		0.22	0.51	
			TA = $+50^\circ\text{C}$		0.27	1.10	
			TA = $+70^\circ\text{C}$		0.37	1.90	
			TA = $+85^\circ\text{C}$		0.60	3.30	
			TA = $+105^\circ\text{C}$		1.50	17.00	

- <R> **Note 1.** Total current flowing into V_{DD} , including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS} . The MAX values include the peripheral operating current. However, these values do not include the current flowing into the A/D converter, operational amplifier, comparator, LVD circuit, I/O ports, and on-chip pull-up/pull-down resistors, and the current flowing during data flash rewrite.
- Note 2.** The values do not include the current flowing into the real-time clock, 12-bit interval timer, and watchdog timer.
- Note 3.** For the setting of the current values when operating the subsystem clock in STOP mode, see the current values when operating the subsystem clock in HALT mode.

UART mode connection diagram (during communication at same potential)**UART mode bit width (during communication at same potential) (reference)**

Remark 1. q: UART number ($q = 0$), g: PIM and POM number ($g = 5$)

Remark 2. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number ($mn = 00, 01$))

(4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, Vss = AVss = 0 V) (1/2)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LP (Low-power main) mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time Note 5	tkcy2	2.7 V ≤ VDD ≤ 3.6 V	fMCK > 16 MHz	8/fMCK		—	—	—	—	—	—	ns
			fMCK ≤ 16 MHz	6/fMCK		6/fMCK		6/fMCK		6/fMCK		
		2.4 V ≤ VDD ≤ 3.6 V		6/fMCK and 500		6/fMCK		6/fMCK		6/fMCK		
		1.8 V ≤ VDD ≤ 3.6 V		—		6/fMCK		6/fMCK		6/fMCK		
		1.7 V ≤ VDD ≤ 3.6 V		—		—		—				
		1.6 V ≤ VDD ≤ 3.6 V		—		—		—				
SCKp high-/low-level width	tkh2, tkl2	2.7 V ≤ VDD ≤ 3.6 V		tkcy2/2 - 8		tkcy2/2 - 8		tkcy2/2 - 8		tkcy2/2 - 8		ns
		2.4 V ≤ VDD ≤ 3.6 V		tkcy2/2 - 18		tkcy2/2 - 18		tkcy2/2 - 18		tkcy2/2 - 18		
		1.8 V ≤ VDD ≤ 3.6 V		—		tkcy2/2 - 66		tkcy2/2 - 66		tkcy2/2 - 66		
		1.7 V ≤ VDD ≤ 3.6 V		—								
		1.6 V ≤ VDD ≤ 3.6 V		—								
Slp setup time (to SCKp↑) Note 1	tsik2	2.7 V ≤ VDD ≤ 3.6 V		1/fMCK + 20	1/fMCK + 30	1/fMCK + 30	1/fMCK + 30	1/fMCK + 30	1/fMCK + 30	1/fMCK + 30	1/fMCK + 30	ns
		2.4 V ≤ VDD ≤ 3.6 V		1/fMCK + 30								
		1.8 V ≤ VDD ≤ 3.6 V		—								
		1.7 V ≤ VDD ≤ 3.6 V		—		—		—		1/fMCK + 40		
		1.6 V ≤ VDD ≤ 3.6 V		—		—		—				
Slp hold time (from SCKp↓) Note 2	tksl2	2.4 V ≤ VDD ≤ 3.6 V		1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	1/fMCK + 31	ns
		1.8 V ≤ VDD ≤ 3.6 V		—								
		1.7 V ≤ VDD ≤ 3.6 V		—		—		—		1/fMCK + 250		
		1.6 V ≤ VDD ≤ 3.6 V		—		—		—				
Delay time from SCKp↓ to SOp output Note 3	tks02	C = 30 pF Note 4	2.7 V ≤ VDD ≤ 3.6 V	2/fMCK + 44	2/fMCK + 110	2/fMCK + 110	2/fMCK + 110	2/fMCK + 110	2/fMCK + 110	2/fMCK + 110	2/fMCK + 110	ns
			2.4 V ≤ VDD ≤ 3.6 V	2/fMCK + 75								
			1.8 V ≤ VDD ≤ 3.6 V	—								
			1.7 V ≤ VDD ≤ 3.6 V	—		—		—				
			1.6 V ≤ VDD ≤ 3.6 V	—		—		—				

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The Slp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 4. C is the load capacitance of the SOp output lines.

Note 5. The maximum transfer rate when using the SNOOZE mode is 1 Mbps.

Caution Select the normal input buffer for the Slp pin and the normal output mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg).

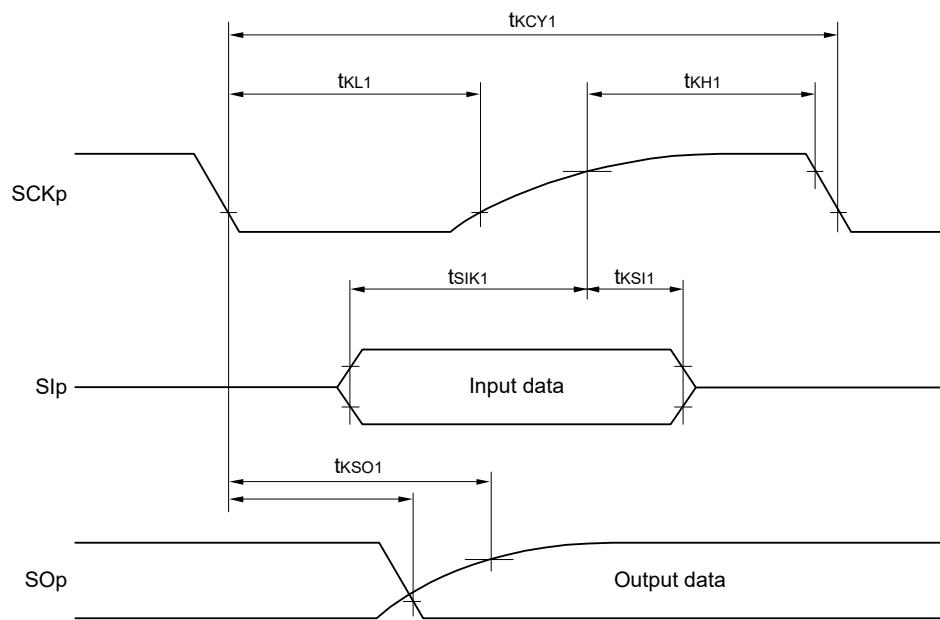
Remark 1. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM numbers (g = 5)

Remark 2. fMCK: Serial array unit operation clock frequency

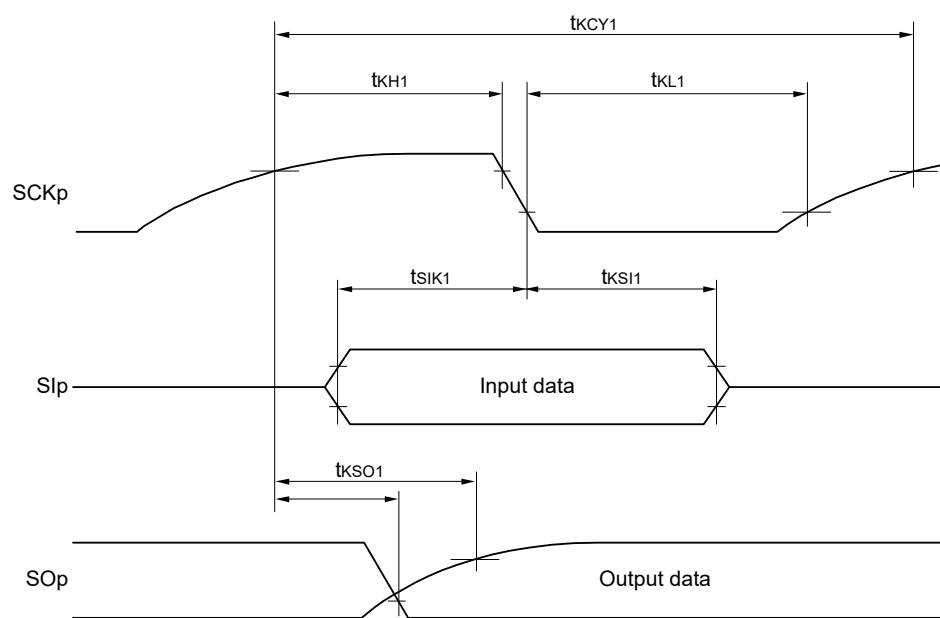
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01))

CSI mode serial transfer timing (master mode) (during communication at different potential)

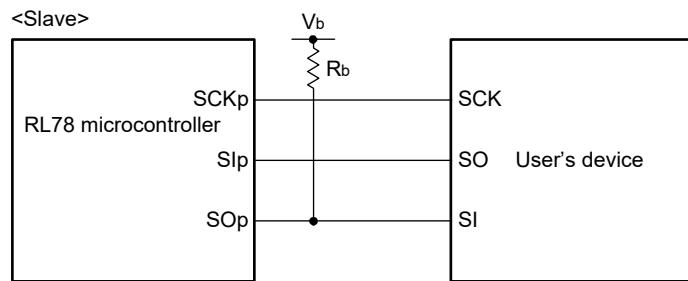
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

**CSI mode serial transfer timing (master mode) (during communication at different potential)**

(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number ($p = 00, 01$), m: Unit number ($m = 0$), n: Channel number ($n = 0, 1$), g: PIM and POM numbers ($g = 5$)

CSI mode connection diagram (during communication at different potential)

Remark 1. $R_b[\Omega]$: Communication line (SO_p) pull-up resistance, $C_b[F]$: Communication line (SO_p) load capacitance, $V_b[V]$: Communication line voltage

Remark 2. p: CSI number (p = 00, 01), m: Unit number (m = 0), n: Channel number (n = 0, 1), g: PIM and POM numbers (g = 5)

Remark 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00, 01))

(10) Communication at different potential (1.8 V, 2.5 V) (simplified I²C mode)

(TA = -40 to 85°C, 1.8 V ≤ AVDD = VDD ≤ 3.6 V, VSS = AVSS = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LP (Low-power main) mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLR clock frequency	f _{SCLR}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ		1000 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ		400 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ		300 Note 1		300 Note 1		250 Note 1		300 Note 1	kHz
Hold time when SCLR = "L"	t _{LOW}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	475		1550		1550		1550		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	1150		1550		1550		1550		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1550		1550		1550		1550		ns
Hold time when SCLR = "H"	t _{HIGH}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	200		610		610		610		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	600		610		610		610		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	610		610		610		610		ns
Data setup time (reception)	t _{SETUP} _{DAT}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	1/f _{MCK} + 135 Note 3		1/f _{MCK} + 190 Note 2		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		1/f _{MCK} + 190 Note 3		ns
Data hold time (transmission)	t _{HD} _{DAT}	2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 50 pF, R _b = 2.7 kΩ	0	305	0	305	0	305	0	305	ns
		2.7 V ≤ V _{DD} ≤ 3.6 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 100 pF, R _b = 2.7 kΩ	0	355	0	355	0	355	0	355	ns
		1.8 V ≤ V _{DD} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V Note 2, C _b = 100 pF, R _b = 5.5 kΩ	0	405	0	405	0	405	0	405	ns

Note 1. The value must also be equal to or less than f_{MCK}/4.**Note 2.** Use it with V_{DD} ≥ V_b.**Note 3.** Set the f_{MCK} value to keep the hold time of SCLR = "L" and SCLR = "H".

Caution Select the TTL input buffer and the N-ch open drain output (V_{DD} tolerance) mode for the SDAr pin and the N-ch open drain output (V_{DD} tolerance) mode for the SCLR pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

- (2) When reference voltage (+) = AVDD (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = AVss (ADREFM = 0), conversion target: ANI0 to ANI13

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = AVDD, Reference voltage (-) = AVss = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES		2.4 V ≤ AVDD ≤ 3.6 V	8		12	bit
			1.8 V ≤ AVDD ≤ 3.6 V	8		10 Note 1	
			1.6 V ≤ AVDD ≤ 3.6 V	8 Note 2			
Overall error Note 3	AINL	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±7.5	LSB
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±5.5	
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±3.0	
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V	3.375			μs
		ADTYP = 0, 10-bit resolution Note 1	1.8 V ≤ AVDD ≤ 3.6 V	6.75			
		ADTYP = 0, 8-bit resolution Note 2	1.6 V ≤ AVDD ≤ 3.6 V	13.5			
		ADTYP = 1, 8-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V	2.5625			
			1.8 V ≤ AVDD ≤ 3.6 V	5.125			
			1.6 V ≤ AVDD ≤ 3.6 V	10.25			
Zero-scale error Note 3	Ezs	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±6.0	LSB
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±5.0	
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±2.5	
Full-scale error Note 3	Efs	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±6.0	LSB
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±5.0	
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±2.5	
Integral linearity error Note 3	ILE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±3.0	LSB
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±2.0	
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±1.5	
Differential linearity error Note 3	DLE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±2.0	LSB
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±2.0	
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±1.5	
Analog input voltage	VAIN	ANI0 to ANI6		0		AVDD	V

Note 1. Cannot be used for lower 2 bit of ADCR register

Note 2. Cannot be used for lower 4 bit of ADCR register

Note 3. Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

- (3) When reference voltage (+) = AVREFP/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), conversion target: ANI16 to ANI18, internal reference voltage, temperature sensor output voltage

(TA = -40 to +85°C, 1.6 V ≤ VDD ≤ 3.6 V, 1.6 V ≤ AVREFP ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V,

Reference voltage (+) = AVREFP, Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Resolution	RES	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	8		12	bit	
		1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	8		10 Note 1		
		1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	8 Note 2				
Overall error Note 3	AINL	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			LSB	
		10-bit resolution	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
		8-bit resolution	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	4.125		μs	
		ADTYP = 0, 10-bit resolution Note 1	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	9.5			
		ADTYP = 0, 8-bit resolution Note 2	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	57.5			
		ADTYP = 1, 8-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	3.3125			
			1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	7.875			
			1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	54.25			
Zero-scale error Note 3	Ezs	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			LSB	
		10-bit resolution	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
		8-bit resolution	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
Full-scale error Note 3	EFS	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			LSB	
		10-bit resolution	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
		8-bit resolution	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
Integral linearity error Note 3	ILE	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			LSB	
		10-bit resolution	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
		8-bit resolution	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
Differential linearity error Note 3	DLE	12-bit resolution	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			LSB	
		10-bit resolution	1.8 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
		8-bit resolution	1.6 V ≤ AVREFP ≤ AVDD ≤ 3.6 V				
Analog input voltage	VAIN			0	AVREFP	V	
		Internal reference voltage (1.8 V ≤ VDD ≤ 3.6 V)		VBGR Note 4			
		Temperature sensor output voltage (1.8 V ≤ VDD ≤ 3.6 V)		VTMP25 Note 4			

Note 1. Cannot be used for lower 2 bits of ADCR register

Note 2. Cannot be used for lower 4 bits of ADCR register

Note 3. Excludes quantization error ($\pm 1/2$ LSB).

Note 4. Refer to 2.6.2 Temperature sensor, internal reference voltage output characteristics.

Caution Always use AVDD pin with the same potential as the VDD pin.

- (4) When reference voltage (+) = AVDD (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = AVss (ADREFM = 0), conversion target: ANI16 to ANI18, internal reference voltage, temperature sensor output voltage

(TA = -40 to +85°C, 1.6 V ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = AVDD, Reference voltage (-) = AVss = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit	
Resolution	RES		2.4 V ≤ AVDD ≤ 3.6 V	8		12	bit	
			1.8 V ≤ AVDD ≤ 3.6 V	8		10 Note 1		
			1.6 V ≤ AVDD ≤ 3.6 V	8 Note 2				
Overall error Note 3	AINL	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±8.5	LSB	
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±6.0		
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±3.5		
Conversion time	tCONV	ADTYP = 0, 12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V	4.125			μs	
		ADTYP = 0, 10-bit resolution Note 1	1.8 V ≤ AVDD ≤ 3.6 V	9.5				
		ADTYP = 0, 8-bit resolution Note 2	1.6 V ≤ AVDD ≤ 3.6 V	57.5				
		ADTYP = 1, 8-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V	3.3125				
			1.8 V ≤ AVDD ≤ 3.6 V	7.875				
			1.6 V ≤ AVDD ≤ 3.6 V	54.25				
Zero-scale error Note 3	Ezs	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±8.0	LSB	
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±5.5		
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±3.0		
Full-scale error Note 3	Efs	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±8.0	LSB	
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±5.5		
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±3.0		
Integral linearity error Note 3	ILE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±3.5	LSB	
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±2.5		
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±1.5		
Differential linearity error Note 3	DLE	12-bit resolution	2.4 V ≤ AVDD ≤ 3.6 V			±2.5	LSB	
		10-bit resolution	1.8 V ≤ AVDD ≤ 3.6 V			±2.5		
		8-bit resolution	1.6 V ≤ AVDD ≤ 3.6 V			±2.0		
Analog input voltage	VAIN			0		AVDD	V	
		Internal reference voltage (1.8 V ≤ VDD ≤ 3.6 V)		VBGR Note 4				
		Temperature sensor output voltage (1.8 V ≤ VDD ≤ 3.6 V)		VTMP25 Note 4				

Note 1. Cannot be used for lower 2 bits of ADCR register

Note 2. Cannot be used for lower 4 bits of ADCR register

Note 3. Excludes quantization error ($\pm 1/2$ LSB).

Note 4. Refer to 2.6.2 Temperature sensor, internal reference voltage output characteristics.

Caution Always use AVDD pin with the same potential as the VDD pin.

- (5) When reference voltage (+) = Internal reference voltage (1.45 V) (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVss (ADREFM = 0), conversion target: ANI0 to ANI13, ANI16 to ANI18

(TA = -40 to +85°C, 1.8 V ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = internal reference voltage, Reference voltage (-) = AVss = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	R _{ES}			8		bit
Conversion time	t _{CONV}	8-bit resolution	16			μs
Zero-scale error Note	E _{zs}	8-bit resolution			±4.0	LSB
Integral linearity error Note	I _{LE}	8-bit resolution			±2.0	LSB
Differential linearity error Note	D _{LE}	8-bit resolution			±2.5	LSB
Analog input voltage	V _{AIN}		0		V _{BGR}	V

Note Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

- (6) When reference voltage (+) = AVREFP/ANI0 (ADREFP1 = 0, ADREFP0 = 1),
reference voltage (-) = AVREFM/ANI1 (ADREFM = 1), conversion target: ANI2 to ANI13

(TA = +85 to +105°C, 2.4 V ≤ AVREFP ≤ AVDD = VDD ≤ 3.6 V, Vss = 0 V, AVss = 0 V, Reference voltage (+) = AVREFP, Reference voltage (-) = AVREFM = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	R _{ES}	2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	8		12	bit
Overall error Note	A _{INL}	12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±6.0	LSB
Conversion time	t _{CONV}	ADTYP = 0, 12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V	3.375			μs
Zero-scale error Note	E _{zs}	12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±4.5	LSB
Full-scale error Note	E _{FS}	12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±4.5	LSB
Integral linearity error Note	I _{LE}	12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±2.0	LSB
Differential linearity error Note	D _{LE}	12-bit resolution 2.4 V ≤ AVREFP ≤ AVDD ≤ 3.6 V			±1.5	LSB
Analog input voltage	V _{AIN}		0		AVREFP	V

Note Excludes quantization error (±1/2 LSB).

Caution Always use AVDD pin with the same potential as the VDD pin.

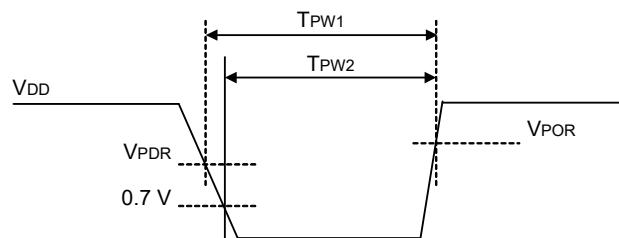
2.6.5 POR circuit characteristics

($T_A = -40$ to $+105^\circ\text{C}$, $V_{ss} = AV_{ss} = 0 \text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	VPOR	Power supply rise time	$T_A = -40$ to $+85^\circ\text{C}$	1.47	1.51	1.55
			$T_A = +85$ to $+105^\circ\text{C}$	1.45	1.51	1.57
	VPDR	Power supply fall time Note 1	$T_A = -40$ to $+85^\circ\text{C}$	1.46	1.50	1.54
			$T_A = +85$ to $+105^\circ\text{C}$	1.44	1.50	1.56
Minimum pulse width Note 2	TPW1	Other than STOP/SUB HALT/SUB RUN	$T_A = +40$ to $+105^\circ\text{C}$	300		μs
	TPW2	STOP/SUB HALT/SUB RUN	$T_A = +40$ to $+105^\circ\text{C}$	300		μs

Note 1. However, when the operating voltage falls while the LVD is off, enter STOP mode, or enable the reset status using the external reset pin before the voltage falls below the operating voltage range shown in 2.4 AC Characteristics.

Note 2. Minimum time required for a POR reset when V_{DD} exceeds below VPDR. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds VPOR while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



2.6.6 LVD circuit characteristics

(1) LVD Detection Voltage of Reset Mode and Interrupt Mode

($T_A = -40$ to $+85^\circ\text{C}$, $V_{PDR} \leq AV_{DD} = V_{DD} \leq 3.6$ V, $V_{SS} = AV_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	Supply voltage level	V _{LVD2}	Power supply rise time	3.07	3.13	V
			Power supply fall time	3.00	3.06	V
		V _{LVD3}	Power supply rise time	2.96	3.02	V
			Power supply fall time	2.90	2.96	V
		V _{LVD4}	Power supply rise time	2.86	2.92	V
			Power supply fall time	2.80	2.86	V
		V _{LVD5}	Power supply rise time	2.76	2.81	V
			Power supply fall time	2.70	2.75	V
		V _{LVD6}	Power supply rise time	2.66	2.71	V
			Power supply fall time	2.60	2.65	V
		V _{LVD7}	Power supply rise time	2.56	2.61	V
			Power supply fall time	2.50	2.55	V
		V _{LVD8}	Power supply rise time	2.45	2.50	V
			Power supply fall time	2.40	2.45	V
		V _{LVD9}	Power supply rise time	2.05	2.09	V
			Power supply fall time	2.00	2.04	V
		V _{LVD10}	Power supply rise time	1.94	1.98	V
			Power supply fall time	1.90	1.94	V
		V _{LVD11}	Power supply rise time	1.84	1.88	V
			Power supply fall time	1.80	1.84	V
		V _{LVD12}	Power supply rise time	1.74	1.77	V
			Power supply fall time	1.70	1.73	V
		V _{LVD13}	Power supply rise time	1.64	1.67	V
			Power supply fall time	1.60	1.63	V
Minimum pulse width	t _{LW}		300			μs
Detection delay time					300	μs

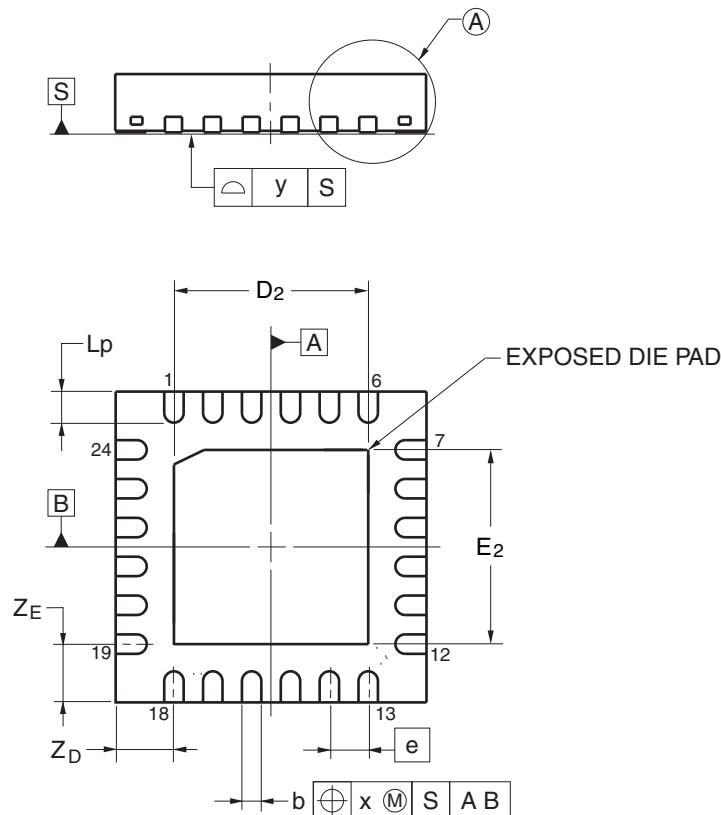
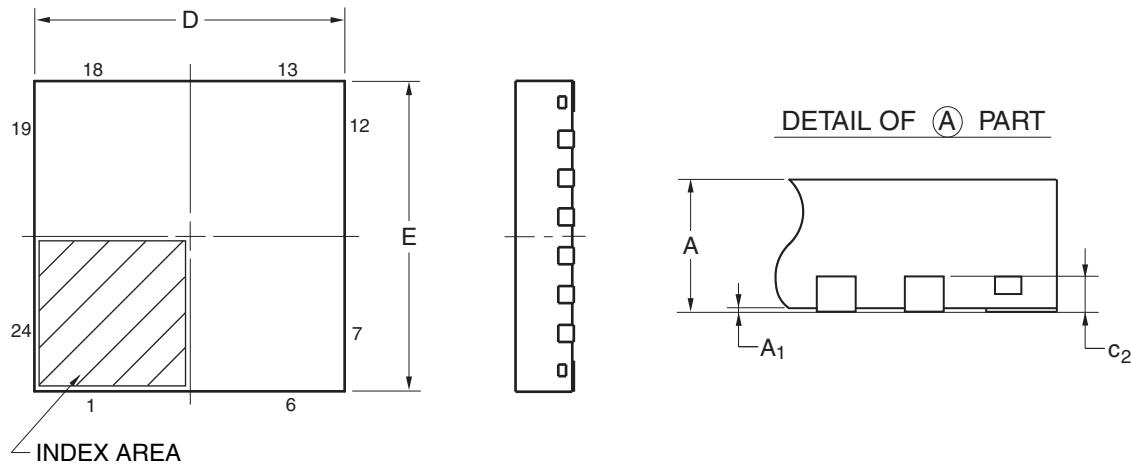
($T_A = +85$ to $+105^\circ\text{C}$, $V_{PDR} \leq AV_{DD} = V_{DD} \leq 3.6$ V, $V_{SS} = AV_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	Supply voltage level	V _{LVD2}	Power supply rise time	3.01	3.13	V
			Power supply fall time	2.94	3.06	V
		V _{LVD3}	Power supply rise time	2.90	3.02	V
			Power supply fall time	2.85	2.96	V
		V _{LVD4}	Power supply rise time	2.81	2.92	V
			Power supply fall time	2.75	2.86	V
		V _{LVD5}	Power supply rise time	2.71	2.81	V
			Power supply fall time	2.64	2.75	V
		V _{LVD6}	Power supply rise time	2.61	2.71	V
			Power supply fall time	2.55	2.65	V
		V _{LVD7}	Power supply rise time	2.51	2.61	V
			Power supply fall time	2.45	2.55	V
Minimum pulse width	t _{LW}		300			μs
Detection delay time					300	μs

3.2 24-pin products

R5F1177AGNA, R5F11778GNA

JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN24-4x4-0.50	PWQN0024KE-A	P24K8-50-CAB-3	0.04



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	3.95	4.00	4.05
E	3.95	4.00	4.05
A	—	—	0.80
A ₁	0.00	—	—
b	0.18	0.25	0.30
e	—	0.50	—
L _p	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05
Z _D	—	0.75	—
Z _E	—	0.75	—
c ₂	0.15	0.20	0.25
D ₂	—	2.50	—
E ₂	—	2.50	—

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3.5 48-pin products

<R> R5F117GCGFB, R5F117GAGFB

